



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC100N03MS G		<b>Issued</b>		19. January 2018	
<b>MA#</b>				MA001308708					
<b>Package</b>				PG-TDSON-8-5		<b>Weight*</b>		118.57 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.709	0.60	0.60	5978	5978	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96		
	non noble metal	copper	7440-50-8	37.762	31.85	31.89	318481	318896	
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	511	511	
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		737		
	plastics	epoxy resin	-	6.201	5.23		52303		
	inorganic material	silicondioxide	60676-86-0	37.383	31.53	36.83	315288	368328	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12243	12243	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1396	1396	
solder	noble metal	silver	7440-22-4	0.026	0.02		220		
	non noble metal	tin	7440-31-5	0.021	0.02		176		
	non noble metal	lead	7439-92-1	0.996	0.84	0.88	8402	8798	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29		
	non noble metal	copper	7440-50-8	11.320	9.55	9.56	95473	95598	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	copper	7440-50-8	22.292	18.80	18.83	188008	188252	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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